MDC200 MDA200 MDK200 MDX200

普通整流管模块

特点

芯片与底板电气绝缘，2500V 交流绝缘

优良的温度特性和功率循环能力

体积小，重量轻

典型应用

交直流电机控制

各种整流电源

变频器

$I_{F(AV)}$	200A
V_{RRM}	600~1800V
I_{FSM}	8 KA
I^2t	326 10^3A^2S

符号		参数	测试条件	结温	参数值	单位
电流额定值	$I_{F(AV)}$	正向平均电流	180° 正弦半波， 50Hz 单面散热，Ths=100° C	150	200	A
	$I_{F(RMS)}$	方均根电流			314	A
	I_{FSM}	通态不重复浪涌电流	10ms 底宽， 正弦半波， VR=0.6VRRM		8.00	KA
	I^2t	浪涌电流平方时间积			326	KA^2S
特性值	V_{RRM}	反向重复峰值电压	V_{RRM} tp=10ms V_{RSM}= V_{RRM}+200V		600~1800	V
	I_{RRM}	反向重复峰值电流	V_{RM}= $_{VRRM}$		12	Ma
	V_{FO}	门槛电压			0.75	V
	r_F	斜率电阻			0.88	mΩ
	V_{FM}	正向峰值电压	I_{TM}=600A	25	1.38	V
	V_{iso}	绝缘电压	50HZ,R.M.S,t=1min,Iiso:1mA(max)		min2500	V
热和机械数据	$R_{th(j-c)}$	热阻抗(结至壳)	180° 正弦半波， 单面散热		max0.210	℃/W
	$R_{th(c-h)}$	热阻抗(壳至散)	180° 正弦半波， 单面散热		max0.08	℃/W
	F_m	安装扭矩（M5）			6	N・m
		安装扭矩(M6)			6	N・m
	T_{stg}	贮存温度			-40~125	℃
	W_t	质量			320	g

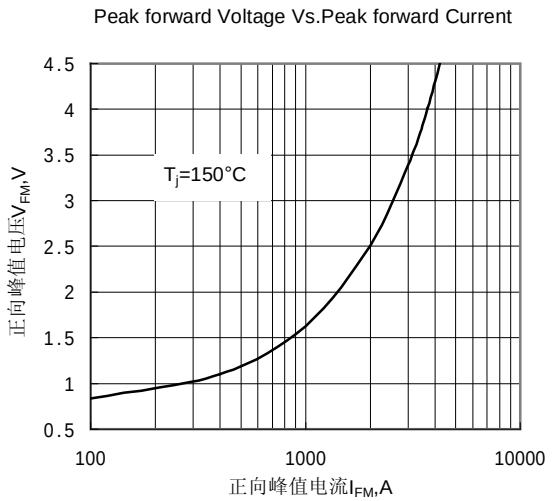


Fig.1 正向伏安特性曲线

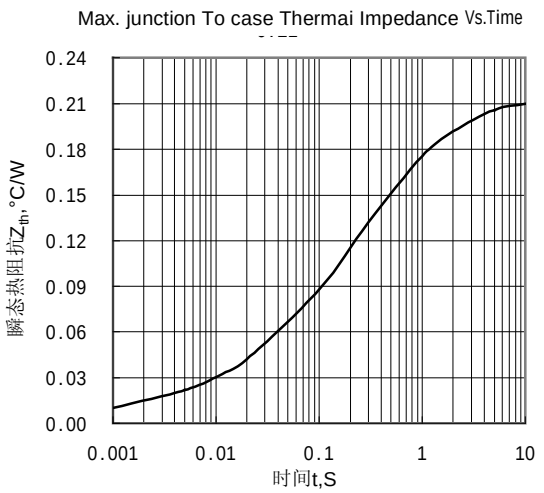


Fig.2 瞬态热阻抗曲线

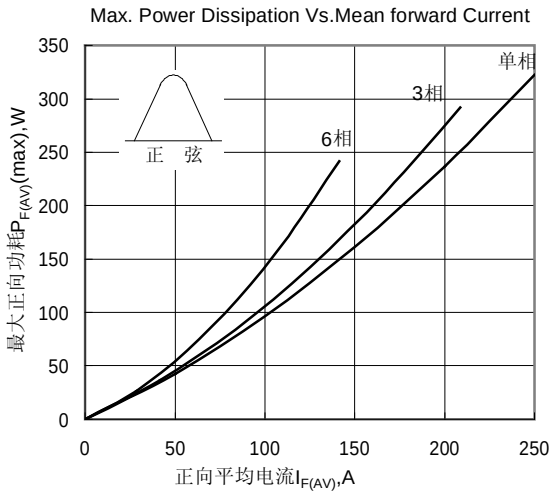


Fig.3最大正向功耗与平均电流的关系曲线

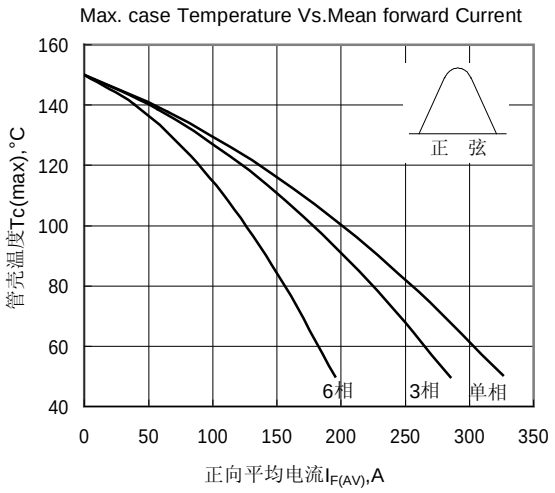


Fig.4管壳温度与正向平均电流的关系曲线

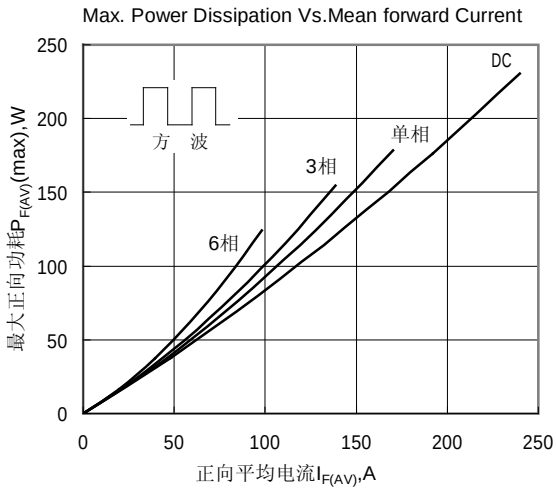


Fig.5最大正向功耗与平均电流的关系曲线

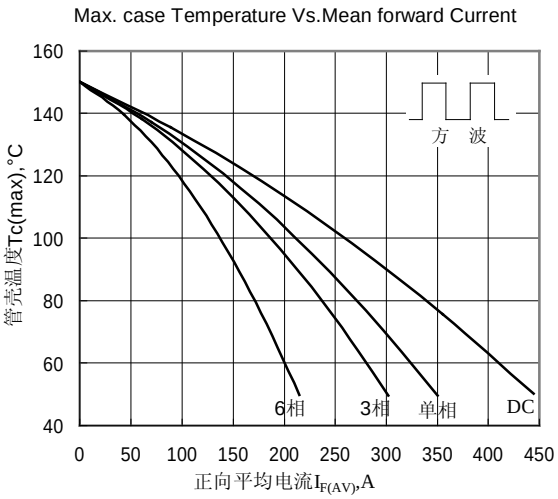


Fig.6管壳温度与正向平均电流的关系曲线

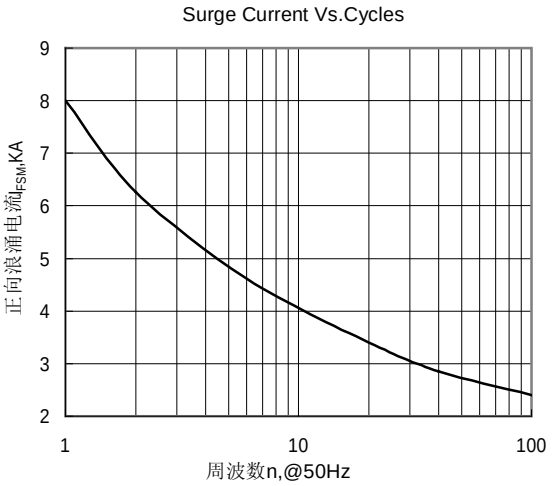


Fig.7 正向浪涌电流与周波数的关系曲线

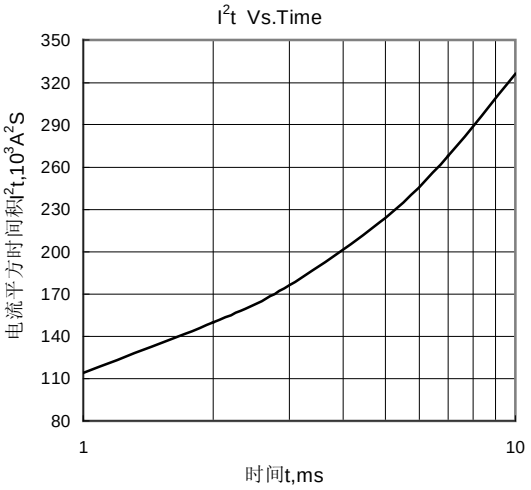
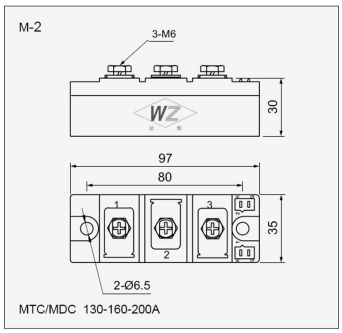
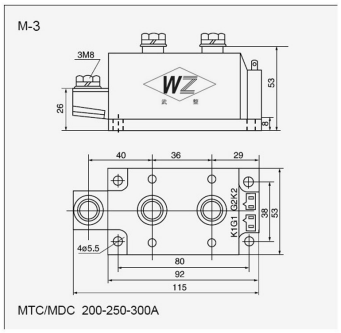
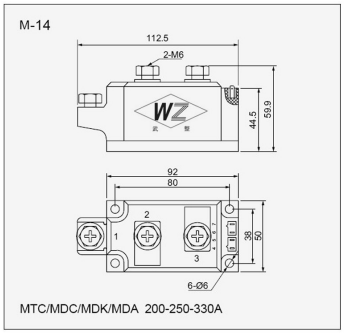
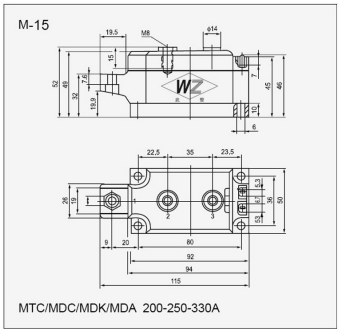
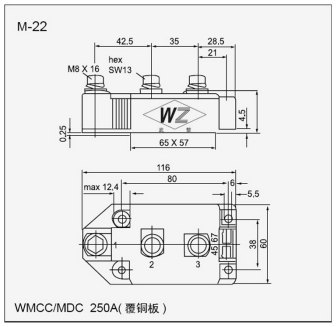
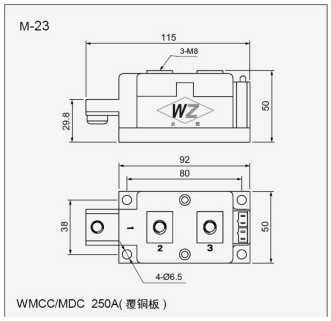
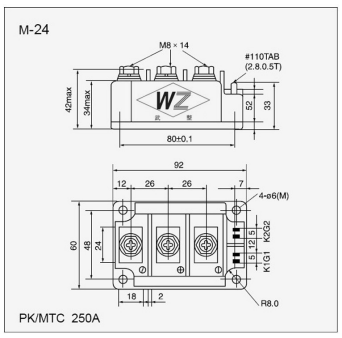
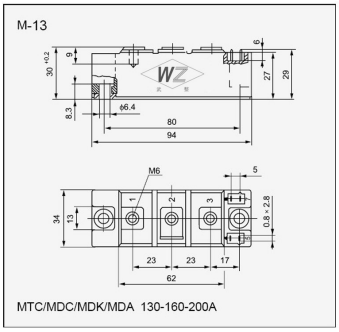
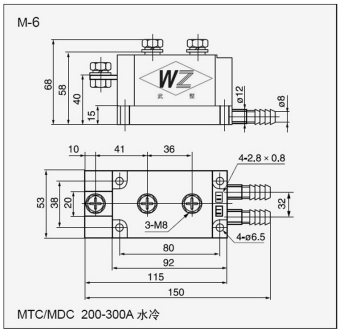


Fig.8 I^2t特性曲线

外形图: